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*Stephen Hordley*

Dated 11 February 2002

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P01/7700 0.00-0100626.1

# Request for grant of a patent

(See the notes on the back of this form. You can also get an explanatory leaflet from the Patent Office to help you fill in this form).

The Patent Office

Cardiff Road  
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1. Your reference **GBP83197**

2. Patent application number  
(The Patent Office will fill in this part)

**0100626.1**

**10 JAN 2001**

3. Full name, address and postcode of the or of each applicant (underline all surnames)

Evenoak Limited  
Rodney Way  
Widford  
Chelmsford  
Essex CM1 3BY

6081087001

Patents ADP number (if you know it)

If the applicant is a corporate body, give the country/state of its incorporation

4. Title of the invention **Nozzle for Soldering Apparatus**

5. Name of your agent (if you have one)  
"Address for service" in the United Kingdom to which all correspondence should be sent (including the postcode)

Marks & Clerk  
57 - 60 Lincolns Inn Fields  
London WC2A 3LS

Patents ADP number (if you know it)

18001 ✓

6. If you are declaring priority from one or more earlier patent applications, give the country and the date of filing of the or of each of these earlier applications and (if you know it) the or each application number

Country

Priority application No  
(if you know it)

Date of filing  
(day / month / year)

7. If this application is divided or otherwise derived from an earlier UK application, give the number and the filing date of the earlier application

Number of earlier application

Date of filing  
(day / month / year)

8. Is a statement of inventorship and of right to grant of a patent required in support of this request? (Answer 'Yes' if:

**Yes**

- a) any applicant named in part 3 is not an inventor, or
  - b) there is an inventor who is not named as an applicant, or
  - c) any named applicant is a corporate body.
- See note (d))

**Patents Form 1/77**

9. Enter the number of sheets for any of the following items you are filing with this form.  
Do not count copies of the same document

Continuation sheets of this form	0
Description	10
Claim(s)	2
Abstract	1
Drawing(s)	5

as 8

10. If you are also filing any of the following, state how many against each item.

Priority documents

Translations of priority documents

Statement of inventorship and right to grant of a patent (Patents Form 7/77)

Request for preliminary examination and search (Patents Form 9/77)

Request for substantive examination (Patents Form 10/77)

Any other documents (please specify)

11.

I/We request the grant of a patent on the basis of this application.

Signature

*M. K. S. K. S. K. S.*

Date: 10 January 2001

12. Name and daytime telephone number of person to contact in the United Kingdom

GB Patent Filings  
0207 400 3000

### Nozzle for Soldering Apparatus

The present invention relates to soldering apparatus, and more particularly to a nozzle for use in a dip soldering process. Such apparatus is described in EP-A-212 911, EP-A-481 710 and EP-A-564 096 for example.

Typically, solder is pumped from a bath upwards through a nozzle, overflowing the nozzle outlet and returning to the bath. A component or circuit board to be soldered is lowered to dip the leads into the surface of solder at the nozzle outlet. Different sizes and shapes of nozzle are provided to suit the particular component or circuit board layout.

When dip soldering a component or circuit board having several closely spaced leads, there is a danger of solder bridging between adjacent leads. This has long been a problem in the art. In US-A- 5 611 480 the problem of solder bridging is overcome by rotating the circuit board as the leads, on the underside of the board, are withdrawn from the surface of the solder.

Rotation of the board or component requires complex apparatus for holding the board or component. The system described in US-A-5 611 480 only rotates the board in one plane. EP-A-860 229 describes a system in which the board can be rotated about different axes, to suit the alignment of the leads being soldered, but a more complex apparatus and control system is required.

With some circuit board arrangements there is not sufficient clearance to rotate the board as it leaves the solder surface.

Another approach is to temporarily reduce or stop the flow of solder through the nozzle, so that the solder surface falls away from the circuit board. This does not require rotation of the board, but it is not particularly successful in avoiding solder bridging.

One aspect of the invention provides a dip soldering method and apparatus in which, during the dipping operation, a plate or other member which is wetted by the solder is positioned between the leads which are being soldered. The plate may be elongate and extend between two rows of leads.

To ensure that sufficient solder is provided to the joints being soldered, the board is usually brought down on to the solder surface or close thereto. Thus, the plate will generally lie just below the solder surface for the initial dipping operation.

The solder surface itself may then be lowered below the upper edge of the plate. This draws the solder away from the joints, reducing the likelihood of solder bridging. However in another method and apparatus, the plate or the like may be raised with the board as the board is lifted away from the solder surface, serving to break through the solder surface and so draw solder down towards the plate.

We have found that with appropriate positioning of the wetted plate and control of the height of the solder surface, we can virtually eliminate the risk of solder bridging.

The shape and positioning of the plate or other wetted member can be tailored to suit the components being soldered. Typically, a soldering machine is set up as part of a production line to solder a run of identical products, and nozzles, for delivering the solder to the underside of the circuit board for example, will be designed to fit around the leads being solder. Where there are two closely spaced rows of leads, the wetted member preferably extends between the rows. It will serve to prevent bridging between the rows and also between adjacent leads in a row. However, a wetted member could be positioned to each outer side of the array. In this latter case, the wetted member could be formed by the nozzle walls themselves.

It is well known in the art that some materials, such as iron, are readily wetted by solder whereas others, such as steel, are not. Even though an iron surface is inherently wetted by solder it is still desirable or necessary to achieve a tinning of the surface to ensure proper wetting of the surface during use. Over time, the surface or member may need re-tinning. Also it may be gradually eroded or eaten away by the constant flow of solder past the surface.

The invention will be further described by way of example, with reference to the accompanying drawings, in which

Figure 1 illustrates schematically a dip soldering apparatus and process of the prior art.

Figure 2 illustrates an embodiment of the invention,

Figures 3a to 3d illustrate the operation of the embodiment of Figure 2;

Figures 4a to 4c illustrate modifications of the embodiment of Figure 2, as partial views on line IV-IV of Figure 3a;

Figure 5 shows a perspective view of a nozzle outlet of the embodiment of Figure 2;

Figure 6 shows another modification of the embodiment of Figure 2;

Figure 7 shows schematically a perspective view of part of a second embodiment of the invention;

Figure 8 shows a side view on Figure 7;

Figure 9 shows a modification.

In the apparatus of Figure 1, a bath 2 contains molten solder 4, which is heated by a heater, not shown. The bath may be covered and/or shrouded in an inert atmosphere such as nitrogen to reduce the formation of dross (oxidised solder). A nozzle 6 is supported on a tubular arm 8 which extends from an impeller housing 10. An impeller 12 is rotated by an



electric motor, not shown, to pump solder 4 through arm 8 into nozzle 6. The speed of impeller 12 is adjusted so that solder overflows an upper edge 13 defining an outlet 14 of nozzle 6. This ensures that a fresh solder surface 15 is continuously provided at the nozzle outlet 14.

A printed circuit board 16 is held by a component holder 18 which translates the board 16 in the horizontal plane X, Y and also lowers the board in the vertical direction Z.

Circuit board 16 has components 20, 22, 24 having leads 25, 26, 27 which extend through the board and are to be soldered to printed circuit tracks (not shown) on the underside 28 of the board 16. To perform the soldering operation, the board 16 is, optionally, first passed through a fluxing station where flux is sprayed onto the areas to be soldered. The board is then positioned over the nozzle 6 and lowered, in the Z direction, to dip leads 26 into the solder surface 15 at the nozzle outlet 14. Typically the board 16 will be lowered until it just presses on the solder surface 15. This will help ensure that solder passes into any through holes in the board and is supplied to the junction between the leads 26 and the printed circuit tracks.

After a predetermined period of time, which ensures that the leads 26 and the adjacent track regions reach a sufficient temperature to retain solder, the board 16 is raised and/or solder surface 15 is lowered. Excess solder will be drawn away from the underside 28 of the board 16 by surface tension. The speed of impeller 12 may be reduced to cause the solder surface 15 to drop away from the board.

When the board 16 has several components to be soldered, the board may be re-positioned to solder the other component leads, additional nozzles may be provided, and/or a larger nozzle may be provided to accommodate leads from more than one component. With closely spaced leads, there is a tendency for excess solder to remain on the board, bridging the leads, as illustrated by leads 27 which are shown as having been soldered already with solder fillets 29. This is very undesirable.

In another type of apparatus, the nozzle 6 may be raised towards the board or component being soldered as described in EP-A-212 911. Also, instead of a constant flow of solder through the nozzle, the nozzle may be in the form of a pot which raised through the surface of the solder in the bath as described in EP-A-481 710.

As mentioned above, US 5 611 480 describes a way of overcoming the problem of solder bridging by rotating the board as it leaves the solder surface. However, in some situations it is not possible to rotate the board in this fashion. For example, there may be components mounted on the underside of the board, which would interfere with the nozzle, or the board may be mounted deep in a housing.

Figure 2 shows an embodiment of the present invention, which is a modification of the apparatus of Figure 1. Like parts have been given like reference numerals.

In Figure 2, a plate 30 is positioned in the nozzle outlet 14. Plate 30 is of a material which is wetted by the solder 4, for example of iron. When board

16 is lowered towards the nozzle 6, the leads 26 pass either side of the plate 30. It is believed that the plate 30 functions to draw more solder away from the underside 28 of the board. Plate 30 is particularly effective if, before the leads 26 are withdrawn, or withdrawn completely, from the solder surface 15, the surface 15 is lowered to below the upper edge 32 of the plate 30, as will be described in more detail with reference to Figure 3.

Referring to Figures 3a to 3xxx, the upper edge 32 of plate 30 is at the same level as the upper edge 34 of the nozzle 6, defining the nozzle outlet 14.

It is preferable that the solder 4 cover the plate 30 during the initial dipping operation, i.e. when the solder is flowing, as illustrated in Figure 3a.

Where one part 13a of the edge 13 is cut away, to give a preferred direction of flow for the overflowing solder, the plate upper edge 32 may be level with the cut away portion. In Figure 3b, the board 16 has been lowered so that the underside 28 of the board 16 just touches the solder surface 15, although it may be stopped just short of this. Solder 4 will flow up the leads 26 to touch the tracks 33 on the underside 28 of the board 16. In Figures 3c and 3d, the speed of impeller 6 has been lowered, to drop the solder surface 15 to below the ends 31 of the leads 26. As the solder surface 15 falls, excess solder is drawn away from the leads 26. By having a wetted surface in the vicinity of the tags 26, provided by plate 30, it is possible to ensure that excess solders not held between the tags 26, which would cause solder bridging. The plate 30 is positioned so that it extends below the ends of the leads, to be interacting with the solder surface 15 as the solder leaves the ends 31 of the leads.

By adjusting the speed at which the solder surface 15 is lowered, or the board raised, the amount of solder retained by the leads 26 can be adjusted.

It will be appreciated that the board 16 may be raised to withdraw the leads 26 from the solder surface 15, as well as lowering the surface 15.

However, it is thought to be necessary for the plate 30 to project through the surface 15 at the time the leads 26 clear the surface 15.

As mentioned above, the shape and size of nozzle outlet 14 will be tailored to suit the array of leads which are to be soldered. Similar the plate(s) 30 may be tailored to suit the array of leads.

Referring to Figure 4a, this shows two rows of leads and a plate 30 extending between them.

In Figure 4b, there are four rows of leads, and three plates 30a, 30b, 30c. However, it will be appreciated that the centre plate 30b might not be necessary. This will depend in part on the spacing between the rows of leads, a narrower spacing giving a higher likelihood of solder bridging.

In Figure 4c, a honeycomb structure is shown.

Figure 5 shows a perspective view of the nozzle outlet 14, with plate 30 supported in rebates 40 in the nozzle side walls 42.

Although an elongate plate provides an effective arrangement for most situations, and is readily mounted in the nozzle outlet, other wetted members are possible. Thus a simple pin shape 44 might be used to fit within an array of three leads 46, as illustrated in Figure 6.

Also, as mentioned above, the wetted plate 30 may be replaced or supplemented by a wetted surface 50 at the nozzle outlet 14. This may be particularly suitable when soldering a single row of closely spaced leads, as illustrated in Figure 6.

Although the wetted member has been shown as extending along the length of a row of leads, it could be provided only at or near the end of a row, for example, in order to target those areas where solder bridging is most prone to occur. Also, while vertical movement of the circuit board is shown, the system may also be used when the board is rotated.

Figure 7 shows a second embodiment in which the wetted member is movable so as to rise through the solder surface 15 as the board 16 is lifted.

The wetted member 68 is in the form of a rod 70 carrying pins 72 which, in use, extend up between leads 26 on the circuit board (see Figure 8). The rod 70 slides in slots 74 in sidewalls 76 of the nozzle 6 and is carried on pivot arms 78. Arms 78 may be biased or electrically controlled to raise and lower the wetted member 68.

As the circuit board 16 is lowered onto the solder surface 15 it will push the pins 72 downwards or they will be driven downwards. As board 16 is raised, and leads 26 start to leave the solder surface 15, the pins 72 will also move upward and through the solder surface, until leads 26 are clear. Thus, the pins 72 will serve to duct excess solder from the leads 26 back to the surface 15. Referring to Figure 9, the wetted member 68 has a shape similar to member 30 of Figure 4c.

**CLAIMS:**

1. Dip soldering apparatus comprising a reservoir for solder into which component leads are dipped, wherein a surface which is wetted by the solder is provided closely adjacent to and facing the leads during dipping.
2. Apparatus for soldering two or more leads to a circuit board, the apparatus including molten solder and the leads being dipped into the molten solder to solder them to the circuit board, wherein a surface which is wetted by the solder is provided in the molten solder in the vicinity of the dipped leads.
3. Dip soldering apparatus comprising a nozzle through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein a surface which is wetted by the solder is provided in the solder at the nozzle outlet.
4. Apparatus as claimed in claim 3, wherein the wetted surface is provided by a member which is below the level of the solder surface as the solder flows through the nozzle outlet.
5. Apparatus as claimed in claim 3, wherein the surface is provided by a member which is movable relative to the solder surface.
6. A method of dip soldering a plurality of closely spaced leads to a circuit board, the leads projecting from an underside of the board, the method comprising dipping the leads into a surface of molten solder to

coat the leads and an adjacent circuit track with solder and withdrawing the leads from the solder surface, wherein a surface which is wetted by the molten solder is provided adjacent the leads, the wetted surface projecting through the solder surface as the leads are withdrawn from the solder.

7. A method as claimed in claim 6, wherein the solder surface is lowered to effect withdrawal of the leads from the solder.



**ABSTRACT**Nozzle for Soldering Apparatus

In a dip soldering process, solder 4 is pumped through a nozzle outlet 14. Leads 26 of a component 22 on a circuit board 16 are dipped into the surface 15 of the flowing solder to solder the leads 26 to a track on the underside 28 of the circuit board 16. To prevent solder bridging between the leads 26, a plate 30 is provided below the solder surface 15, and passes between the leads 26. When withdrawing the leads 26 from the solder, the solder surface 15 is dropped to the level of the plate 30, so that excess solder is drawn away from the leads, preventing solder bridging between the leads 26. Member 30 may be movable to rise through the solder surface 15 as the circuit board 16 is raised away from the surface.

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PRIOR ART

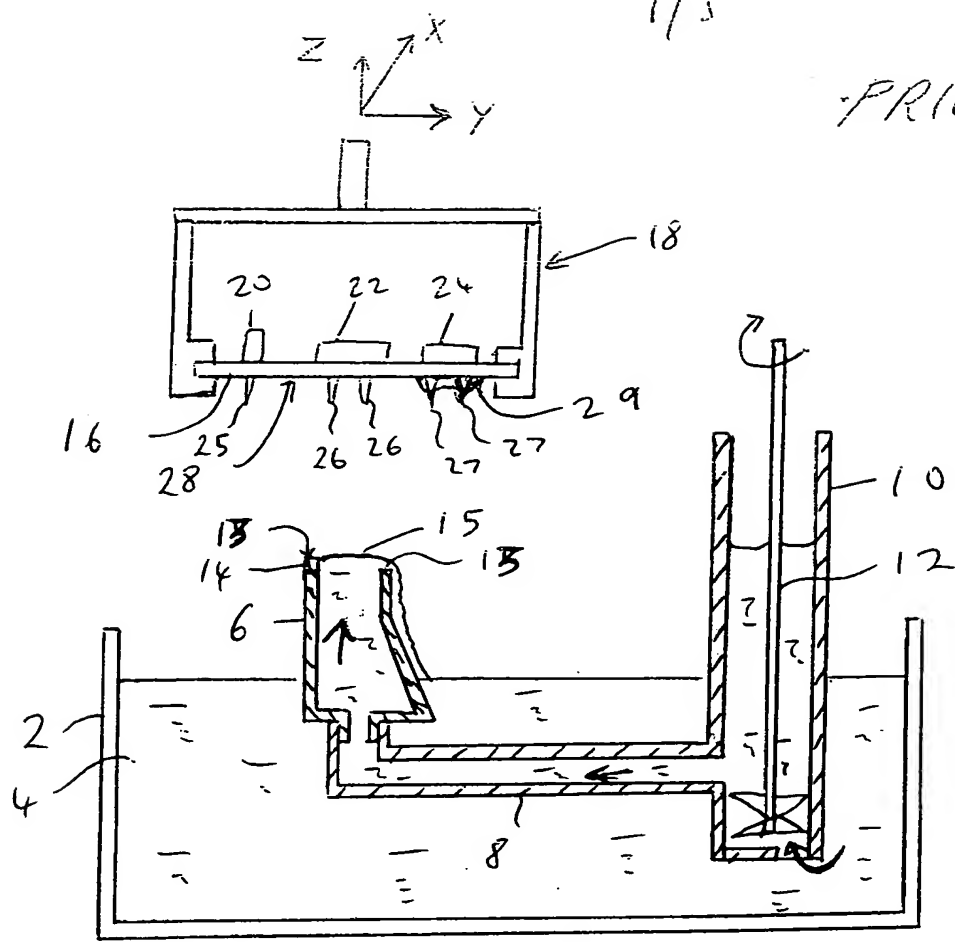


Fig 1

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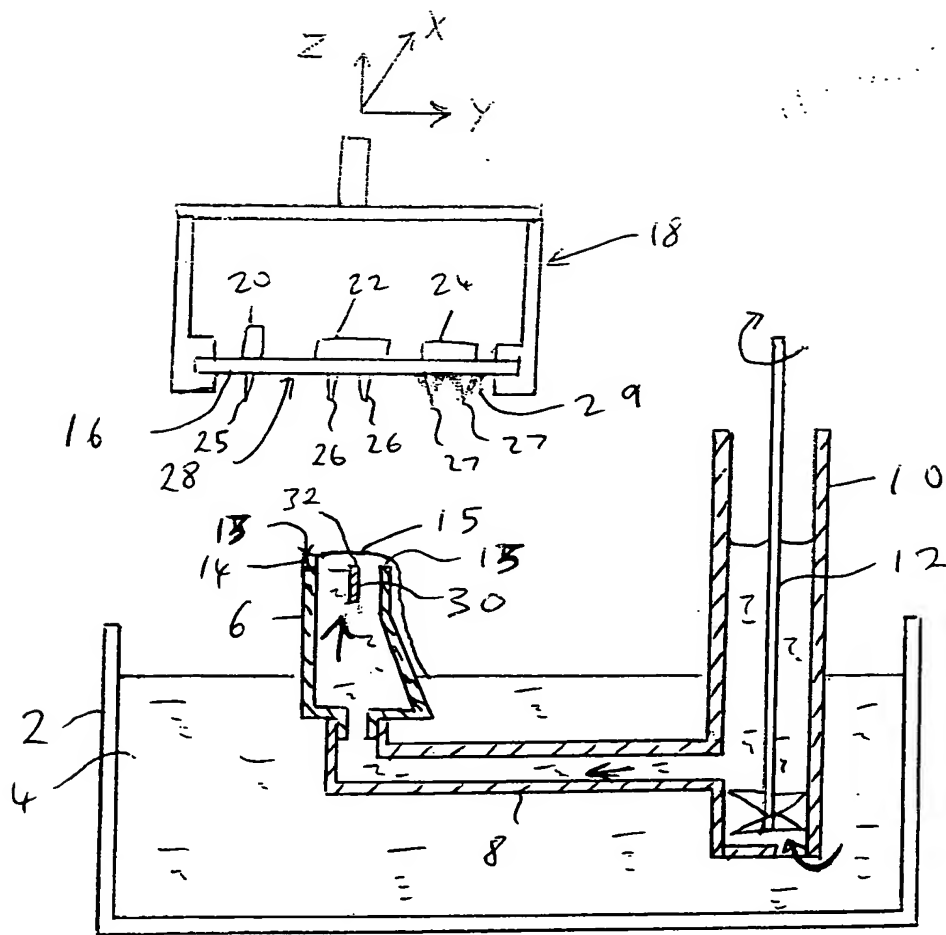


Fig. 2

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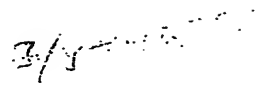
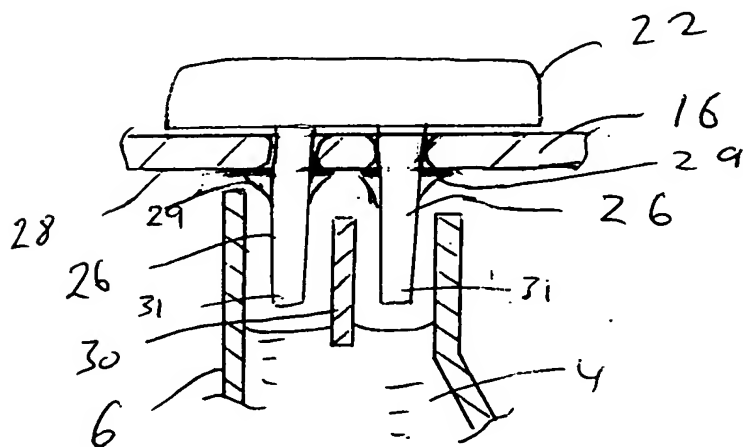
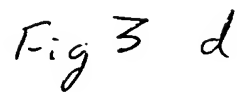
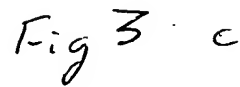


Fig 3 b



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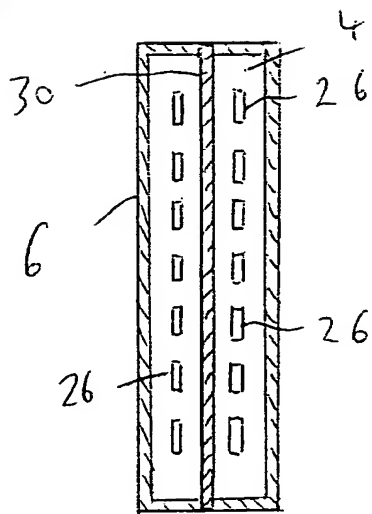


Fig 4a

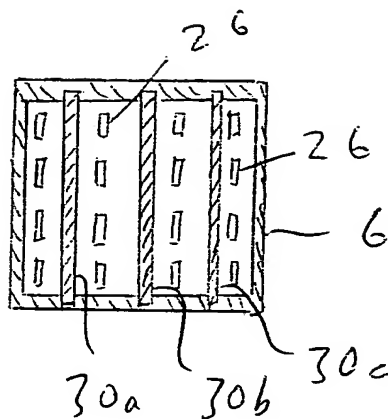


Fig 4b

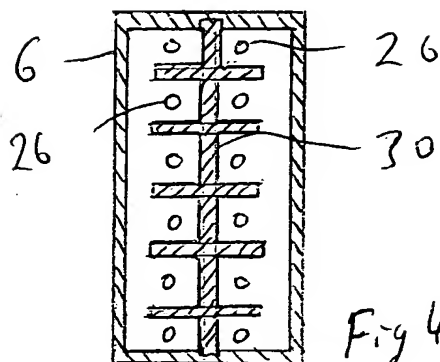


Fig 4c

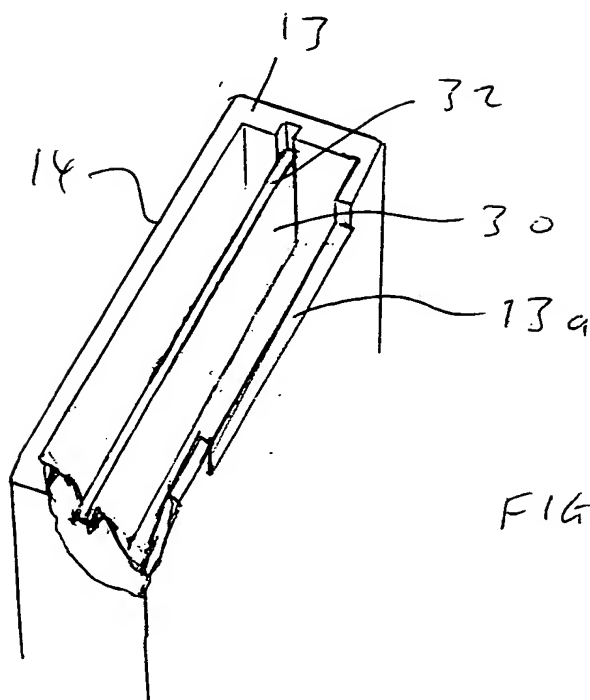


FIG 5

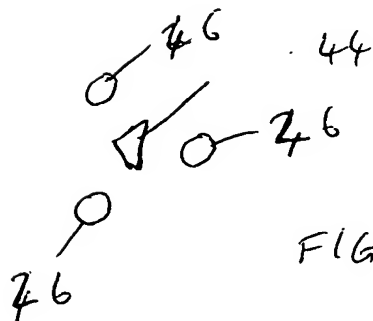


FIG 6

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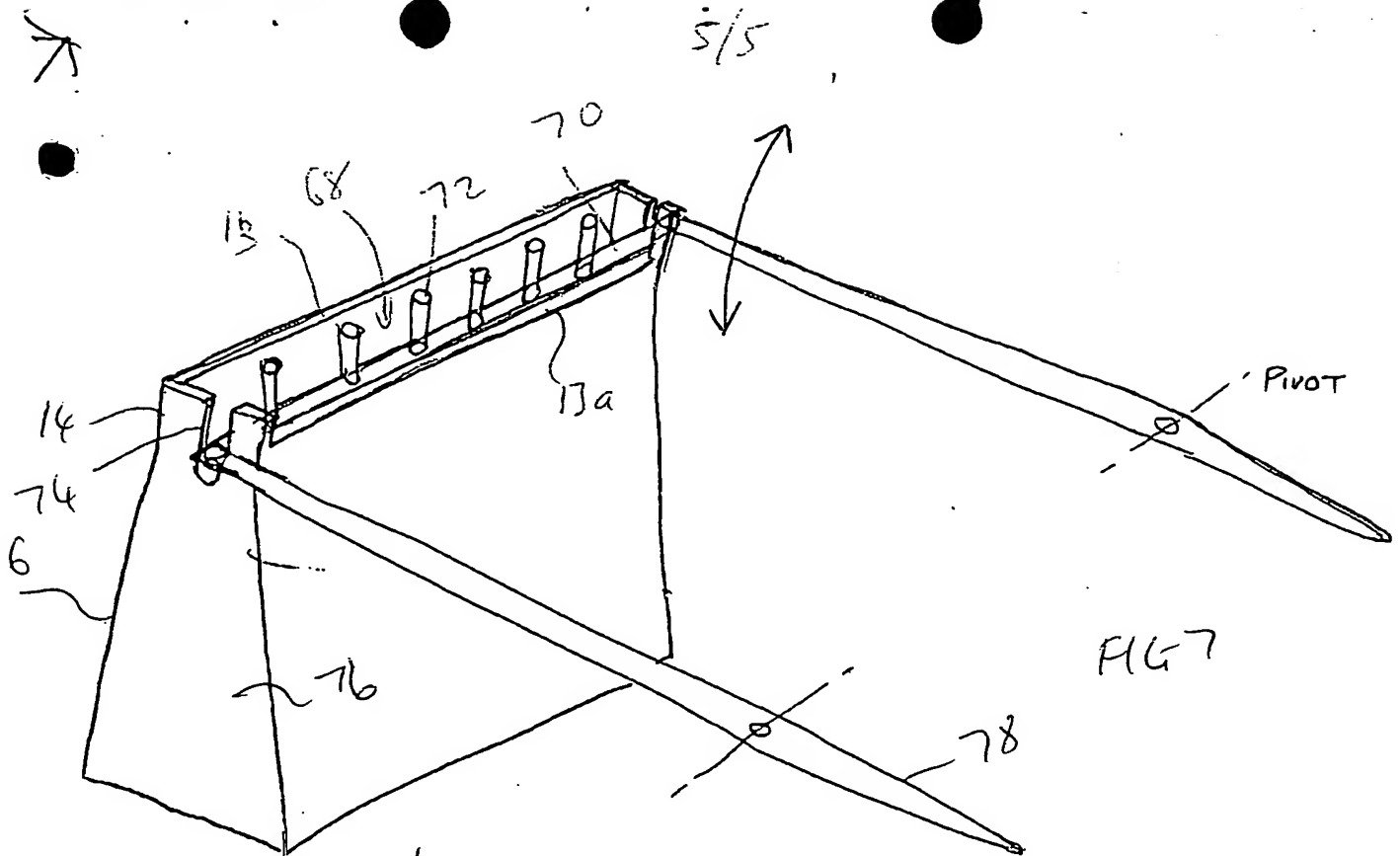


FIG 7

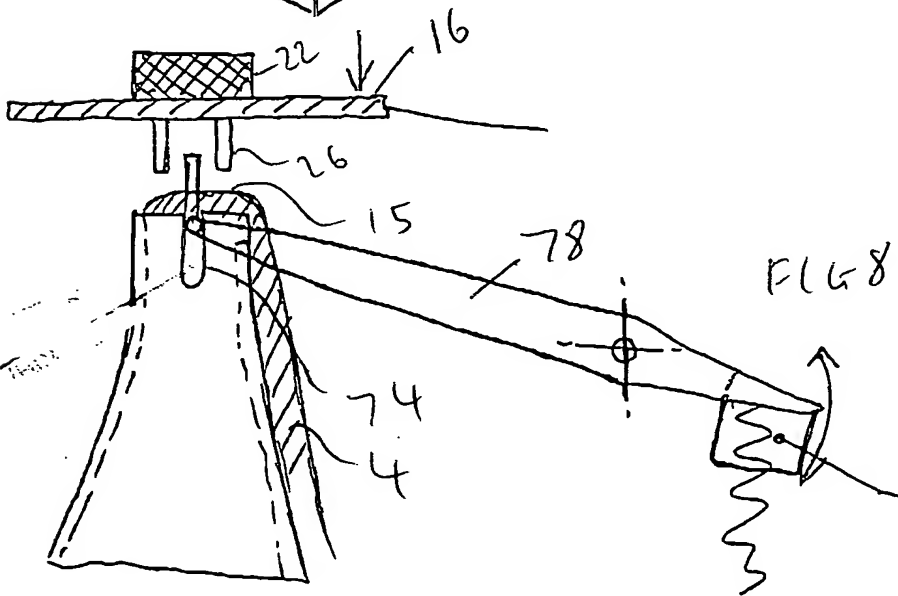


FIG 8

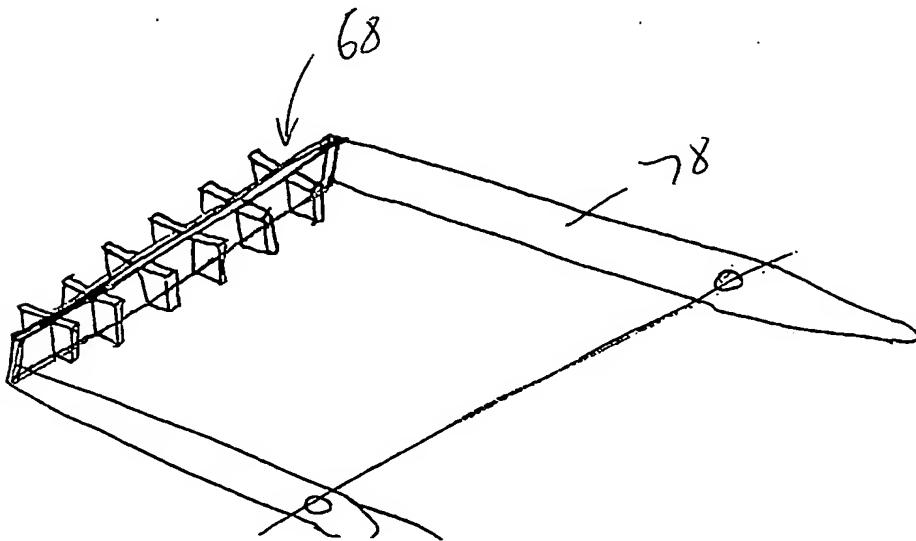


FIG 9

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